

CLAIMS

What is claimed is:

1. A light-emitting-diode chip package comprising:
a base;
an array of light-emitting-diode chips disposed on the base; and
a collimator mounted on the base, over the array of light-emitting-diode chips.
2. The light-emitting-diode chip package according to claim 1, wherein the light-emitting-diode chips are arranged in the array in an inline manner.
3. The light-emitting-diode chip package according to claim 2, wherein the light-emitting-diode chips at ends of the array emit the same color light.
4. The light-emitting-diode chip package according to claim 2, wherein the light-emitting-diode chips at ends of the array emit green light.
5. The light-emitting-diode chip package according to claim 2, wherein the light-emitting-diode chips include a light-emitting-diode chip that emits blue light, a light-emitting-diode chip that emits green light, and a light-emitting-diode chip that emits red light.
6. The light-emitting-diode chip package according to claim 5, wherein the array of light-emitting-diode chips produce a single unit of white light.

7. The light-emitting-diode chip package according to claim 1, wherein the light-emitting-diode chips include a light-emitting-diode chip that emits blue light, a light-emitting-diode chip that emits green light, and a light-emitting-diode chip that emits red light.
8. The light-emitting-diode chip package according to claim 1, wherein the array of light-emitting-diode chips produces a single unit of white light.
9. The light-emitting-diode chip package according to claim 1, wherein the collimator is generally configured as a rectangular, horn-like member.
10. The light-emitting-diode chip package according to claim 9, wherein the collimator includes a first set of walls that collimate the light emitted by the light-emitting-diode chips in a first direction and a second set of walls that minimally collimate the light emitted by the light-emitting-diode chips in a second direction.
11. The light-emitting-diode chip package according to claim 1, wherein the collimator includes a first set of walls that collimate the light emitted by the light-emitting-diode chips in a first direction and a second set of walls that minimally collimate the light emitted by the light-emitting-diode chips in a second direction.
12. The light-emitting-diode chip package according to claim 1, wherein the base is adapted for bonding lead wires.

13. A light source comprising:
- at least two light-emitting-diode chip packages;
 - each of the light-emitting-diode chip packages including:
 - a base;
 - an array of light-emitting-diode chips disposed on the base; and
 - a collimator mounted on the base, over the array of light-emitting-diode chips.
14. The light source according to claim 13, wherein the light-emitting-diode chips are arranged in each of the arrays in an inline manner.
15. The light source according to claim 13, wherein each of the arrays of light-emitting-diode chips includes a light-emitting-diode chip that emits blue light, a light-emitting-diode chip that emits green light, and a light-emitting-diode chip that emits red light.
16. The light source according to claim 13, wherein each of the arrays of light-emitting-diode chips produces a single unit of white light.
17. The light source according to claim 13, wherein each of the collimators is generally configured as a rectangular, horn-like member.
18. The light source according to claim 13, wherein each of the collimators includes a first set of walls that collimate the light emitted by their respective light-emitting-diode

chips in a first direction and a second set of walls that minimally collimate the light emitted by their respective light-emitting-diode chips in a second direction.

19. The light source according to claim 13, wherein each of the bases is adapted for bonding lead wires.